



Material Content Data Sheet



Sales Product Name		IPD50R380CE		Issued		19. January 2018		
MA#		MA001816490						
Package		PG-TO252-3-344		Weight*		323.48 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.808	1.18	1.18	11773	11773
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		134	
	non noble metal	iron	7439-89-6	0.144	0.04		445	
	non noble metal	copper	7440-50-8	143.904	44.48	44.53	444870	445449
	non noble metal	aluminium	7429-90-5	0.443	0.14	0.14	1371	1371
wire	non noble metal	aluminium	7429-90-5	0.443	0.14	0.14	1371	1371
encapsulation	organic material	carbon black	1333-86-4	0.675	0.21		2086	
	plastics	epoxy resin	-	18.222	5.63		56332	
	inorganic material	silicondioxide	60676-86-0	116.082	35.89	41.73	358858	417276
leadfinish	non noble metal	tin	7440-31-5	3.834	1.19	1.19	11851	11851
solder	non noble metal	tin	7440-31-5	0.066	0.02		203	
	noble metal	silver	7440-22-4	0.082	0.03		254	
	non noble metal	lead	7439-92-1	3.134	0.97	1.02	9689	10146
heatspreader	inorganic material	phosphorus	7723-14-0	0.010	0.00		31	
	non noble metal	iron	7439-89-6	0.033	0.01		102	
	non noble metal	copper	7440-50-8	32.995	10.20	10.21	102001	102134
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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